



VERTEX 2020

Latest developments and results of radiation tolerance CMOS sensors with small collection electrodes



Ignacio Asensi on behalf of Phil Allport, Tobias Bisanz, Daniela Bortoletto, Valerio Dao, Dominik Dobrijevic, Mateusz Dyndal, Leyre Flores, Patrick Freeman, Andrea Gabrielli, Laura Gonella, Maria Mironova, Kaan Oyulmaz, Heinz Pernegger, Petra Riedler, Jose Torres, Abhishek Sharma, Carlos Solans, Walter Snoeys, Steven Worm...



LHC Introduction



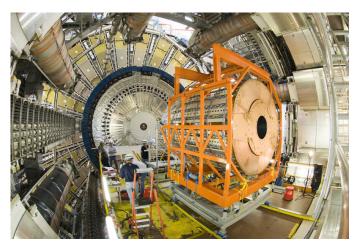
- LHC is going through a series of upgrades
- HL-LHC will deliver 3000 fb⁻¹ after Phase II
- Luminosities from 7.5 to 30 x 10³⁴ cm⁻² s⁻¹
- And from 200 up to 1000 interactions per bunch crossing
- These upgrades present many challenges for electronics and radiation hardness
- Monolithic pixel detectors could address these challenges for the LHC and beyond





Pixel sensors at the LHC





ATLAS Inner detector



CMS pixel detector

- Higher rates of ~2MHz/mm² require smaller sensors to separate individual particles
- Pixel detectors have to overcome high radiation requirements of 1e15 to 2e15 n_{eq}/cm² NIEL
- Pixel detectors can overcome fast timing of 25ns bunch crossing
- Interesting for studies beyond HL-LHC
 - FCC recommended by 2020 Update of the European Strategy for Particle Physics
 - Monolithic pixel sensors present a high potential for HEP with low power consumption (<0.5W/cm²) and industrial-like production



Depleted Monolithic Active Pixel Sensors



RnD designs for Depleted Monolithic Active Pixel Sensors (MAPS) on the search for best performance and radiation hardness

- Large electrode
 - Large capacitance (~100 fF)
 - Electronics in collection well
 - Higher noise (due to larger sensor capacitance)
 - Potential crosstalk between digital and analog sections

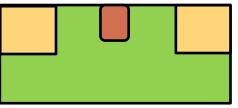
Small electrode

- Low capacitance (~5 fF)
- Electronics separated from collection well
- Lower noise (small capacitance for high SNR)
- Separate digital and analog electronics
- Need process modification for radiation hardness

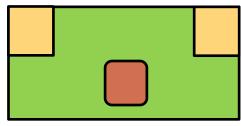
Buried electrode

- Separated layers for electronics and sensor
- To overcome radiation ionization charge trapped in the non depleted part

Large electrode



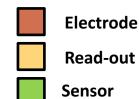
Small electrode

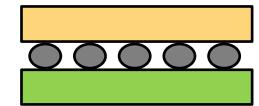


Buried electrode

To be compared with Hybrid sensors

- More expensive and complex
- Two chips: Sensor and a read-out chips
- Large electrodes and large capacitance
- Buried electrodes







TowerJazz 180 nm CMOS technology

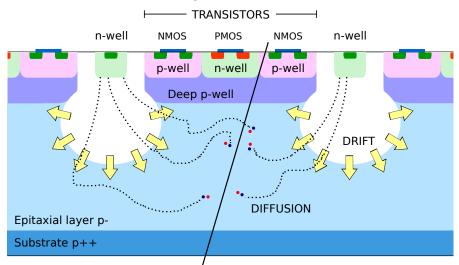


Processes already used in Alice (ALPIDE)

Standard

- Small collection electrode (~3 μm²)
 with high-resistivity Epi layer
- Small input capacitance (< 3 fF)
- Small depletion depth (~20 μm)
- High signal to noise ratio (~20)

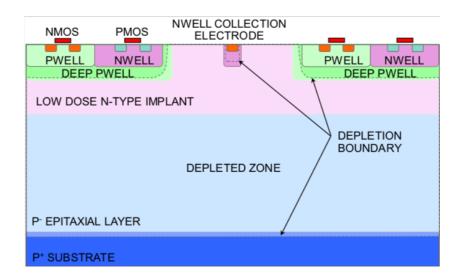
Standard process



Modified with continuous n-layer

- Extra n-type layer to improve depletion under the deep p-well
- Overcome diffusion which makes collection slower

Continuous N-layer



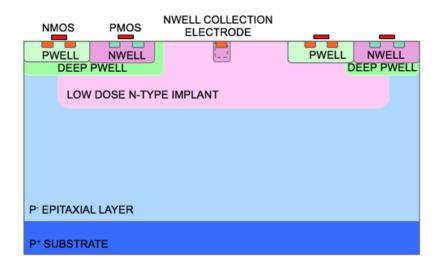
W. Snoeys, NIM A 871 (2017) 90-96



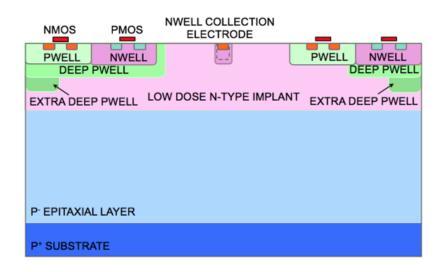
TowerJazz 180 nm CMOS technology



Gap in the n-layer



Extra deep p-well



More details and description of the process modification and summary of results in:

M. Dyndal, JINST 15 (2020) P02005

M. Mironova, NIM A 956 (2020) 163381

Magdalena, M. Munker PIXEL 2018

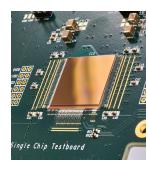
Process modifications for radiation hardness

- Continuous n-layer (Cont.): Full lateral depletion.
 (See prev. slide)
- Gap in the n-layer (n-gap): Modification of the mask
- **Extra deep p-well implant (EDPW)**: Additional mask



Development





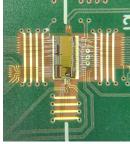
Jan 2018 Jun 2018 **MALTA1 & MLVL**

Sensor modifications

- Continuous n-layer
- **MLVLC**

Chip Large demonstrator 2x2

- Asynchronous readout
- Slowcontrol issues



From Jan 2019

Mini-MALTA And

Mini-MALTA ATTRACT

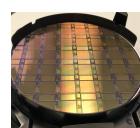
Cascoded FE

Process modification

Small demonstrator 1.7x0.5

Serial output

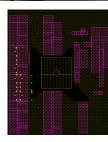
Full efficiency after 1e15 n/cm²



From **Aug 2019** **MALTA C** and **MALTA Cz**

3 types of process modification Large demonstrator 2x2 Slow control improvements

Enlarged cluster size and improved time resolution



Oct 2020 MALTA 2

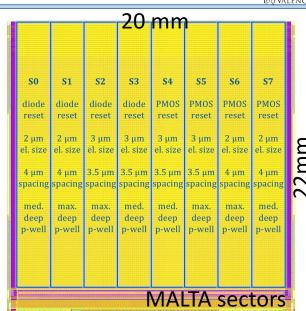
- Mini-MALTA FE
- 3 types of process modification
- Different doping levels
- Smaller matrix 2x1
- **New Slowcontrol**
- Baseline for CERN EP R&D WP 1.2

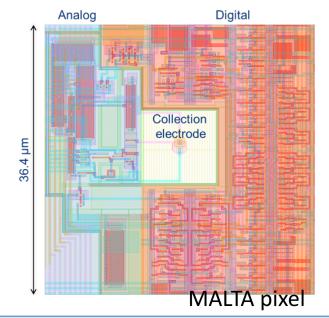


TJ MALTA sensor



- Matrix 512 x 512 pixels of 36.4 x 36.4 μm² size
- 8 sectors with different pixel flavors
- Fully clock-less matrix architecture
- Asynchronous readout architecture for high hit rates and fast signal response.
 Parallel read-out bus 37bit.
- 10 mW/cm² digital power
- Small collection electrode of 2-3 μm to achieve minimal capacitance <3fF
- 3.4 4 μm spacing to electronics
- Very low power consumption:
 - 1 μW/pixel analog power
 - 70 mW/cm² analog power







Possible MALTA application

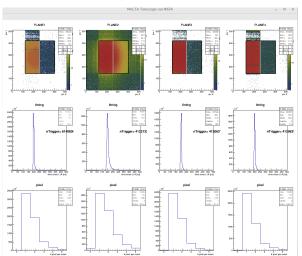


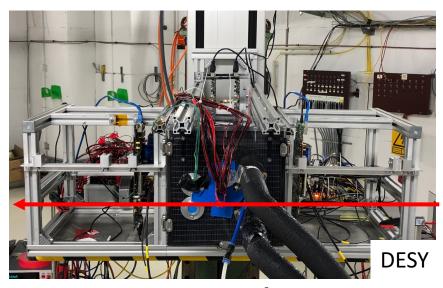
Using MALTA to trigger telescope

- Xilinx Virtex-7 FPGA VC707 for readout
- Trigger from MALTA planes as combination reference signals and compatible with AIDA telescopes

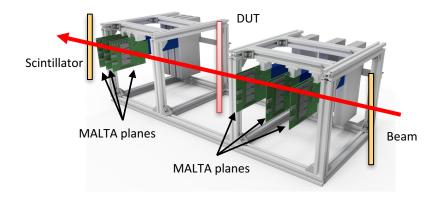
Telescope details:

- 4 to 6 MALTA planes (100 μm thick, 36μm pitch size)
- Achieving 14 μm track-hit resolution using only 3 tracking planes and General Broken Line (GBL) algorithm in Proteus with 3 e⁻ GeV beam in DESY
- Carry-on telescope during LS2 with linear stage for alignment
- Based on custom multi threaded application
- USB based PSU control





Setup with DUT cold down to -20℃ by Si-oil system

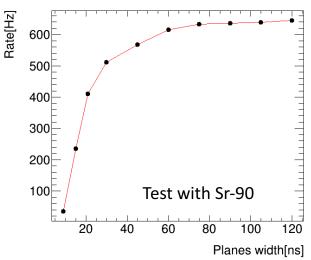


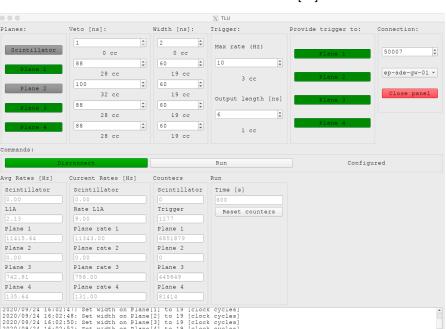
Improved DAQ interface



MALTA telescope TLU



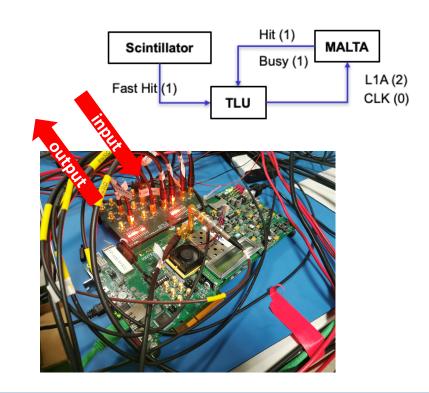




TLU GUI operating and monitoring telescope

Custom Kintex based Trigger Logic Unit (TLU)

- VHDL FW, CMS IPbus and C++/python driven
- Veto, signals width and combination logic configurable from GUI
- Support for scintillator and up to 6 planes



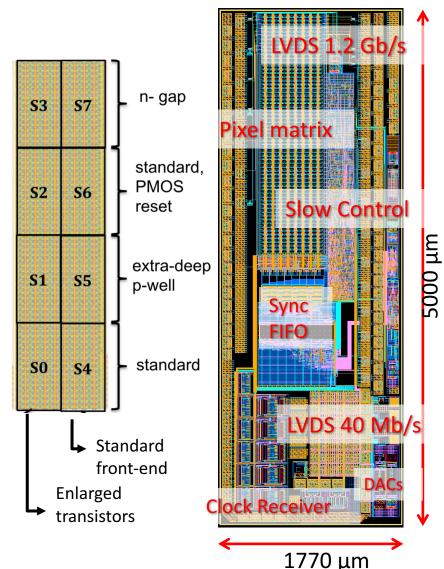


TJ Mini-MALTA sensor



Aim to improve MALTA efficiency loss after irradiation

- Matrix 64x16 pixel with 36.4μm pitch
- 8 sectors with different analogue frontend design
- Asynchronous read-out
- Improved SlowControl implementation
- Single serial data stream: 40Mbs or 1.2
 Gpbs with 8b10b encoding
- Implemented gap in n- layer and extra deep p-well process modifications
- Periphery data synchronization using a custom RAM memory
- Larger capacitors to reduce noise

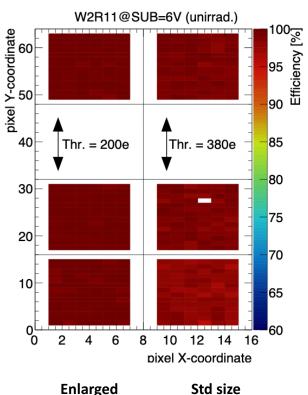




Mini-MALTA efficiency map

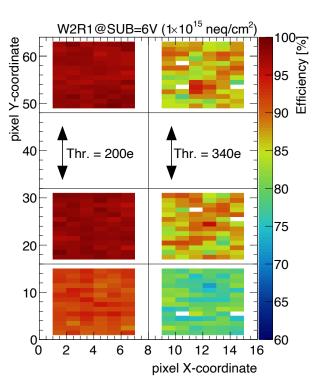






transistors

Irradiated*



- Full efficiency after irradiation at 200 e-threshold at 6V bias on sectors with enlarged transistors
- Due to improved charge collection in the pixel corners with respect to previous design (MALTA 1)
- Also observed with focused x-ray beam at Diamond Light Source (next slide)

Enlarged

transistors

transistors

Std size

transistors

^{*} Irradiated to 1e15 n/cm², and measured with 2 GeV electron beam at ELSA, with 6 V bias voltage.

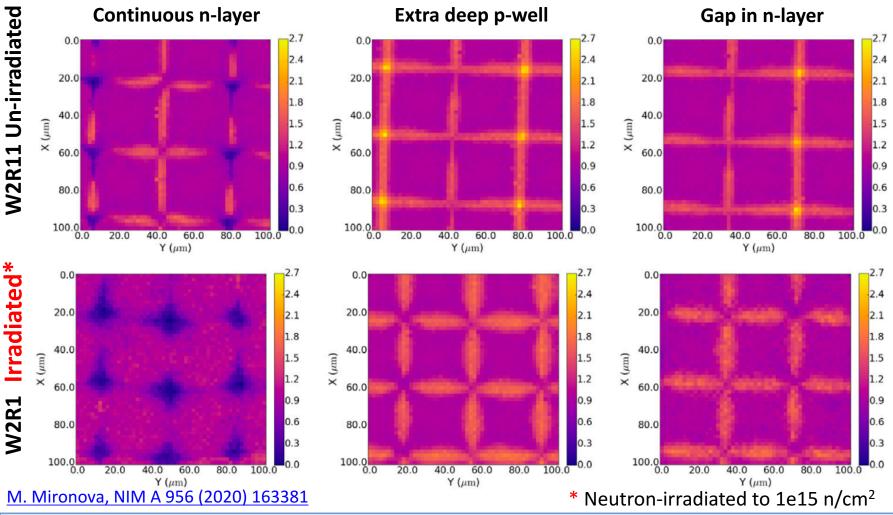


Mini-MALTA at Diamond



Photon pixel response as function of dose

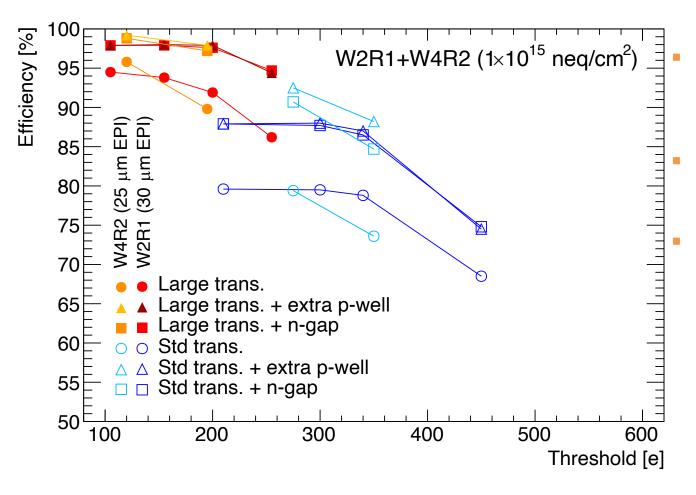
- Reduction of pixel response in continuous n-layer of 10%
- Almost no reduction on extra deep p-well and n-gap





Mini-MALTA efficiency vs threshold





Efficiency above 97% sensor modification with enlarged transitions

Higher efficiency for enlarged transistors

Efficiency above 90% after 2e15 n_{eq}/cm² irradiation (see backup slide)

Efficiency versus threshold for two different Mini-MALTA samples, neutron irradiated to 1e15 n_{eq}/cm^2 , and measured with 2 GeV electron beam at ELSA, with 6 V bias voltage



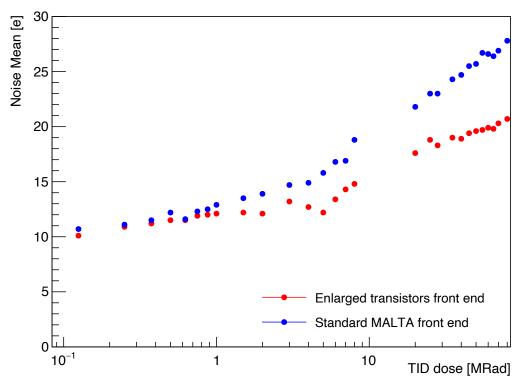
Mini-MALTA - Noise after 100Mrad



Mini-MALTA x-ray irradiated to a TID 100 Mrad Fe fluorescense

X-ray irradiations at Glasgow
Noise mean vs TID

- Noise increase 10e⁻ to 20e⁻ during irradiation on enlarged transistors
- 10e⁻ to 30e⁻ on standard front-end





Mini-MALTA - Noise and gain after 100Mrad

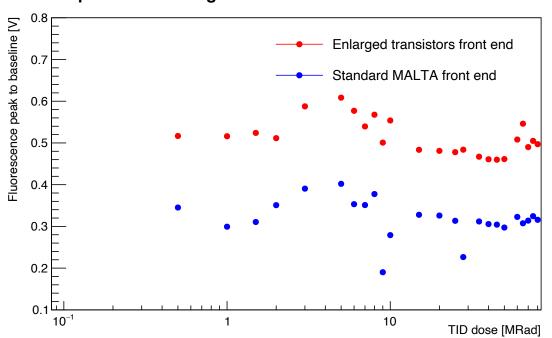


Mini-MALTA γ-irradiated to a TID 100 Mrad Fe fluorescense

X-ray irradiations at Glasgow

Amplitude of FE target as a funcion of TID

- Analog performance measured during irradiation
- Higher gain for enlarged transistors
- Unchanged after dose but with slight increase and then stabilization



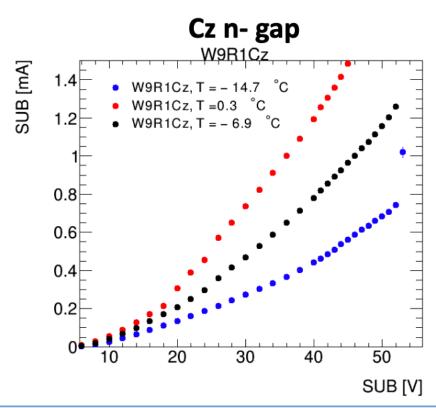


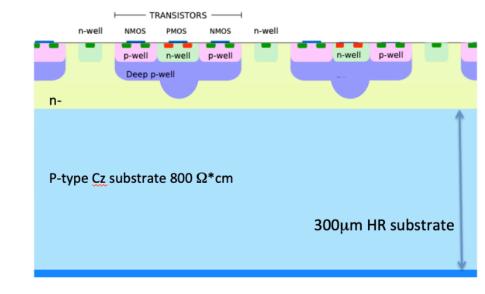
MALTA Czochralski (Cz)



Processed with high resistivity Cz substrate material

- Larger depletion voltage and signal
- Higher radiation hardness
- High operation voltage up to 50V
 - High depletion depth



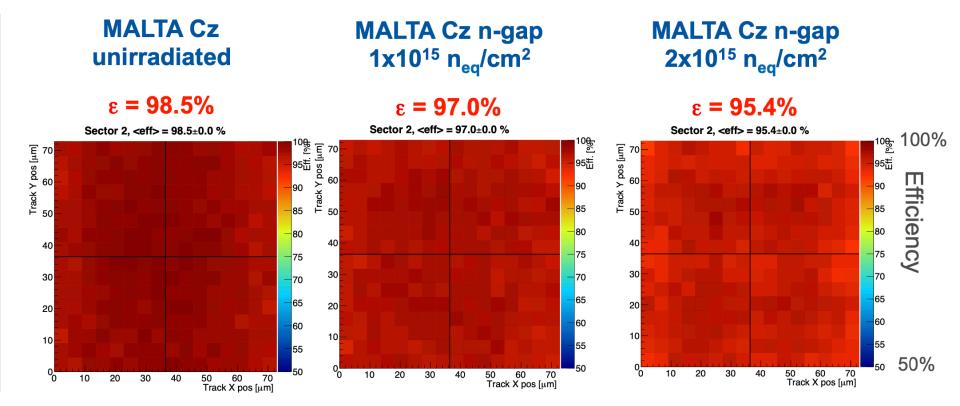




MALTA CZ - Efficiency



- Radiation hardness of full size MALTA with Cz
- From 98.5 (un-irradiated) to 95.4 % efficiency after 2x10¹⁵ n/cm²
 Irradiated at DESY with 4 GeV electron beam

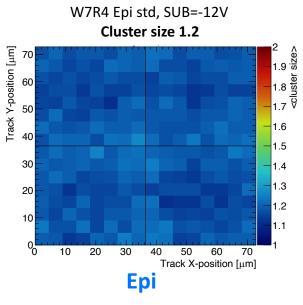


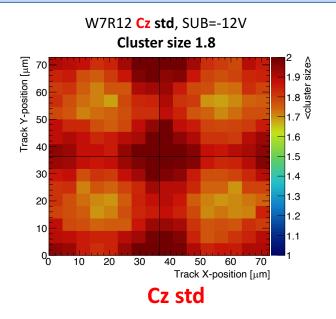
Check Hiroshima Presentation H.Pernegger HSTD12

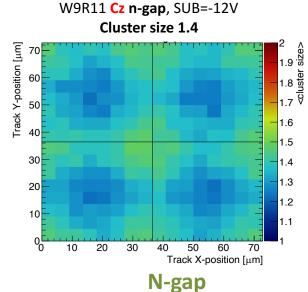


Cluster size - Epi vs Cz std and n-gap



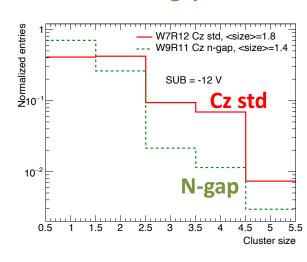


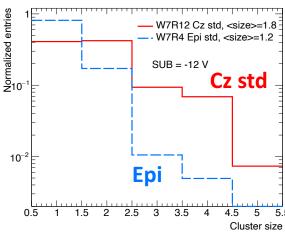




Before irradiation

- Cz has higher cluster size (1.8)
- And more charge collection sharing
- N-gap modification has worse performance

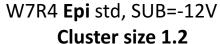


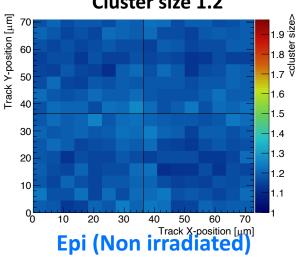




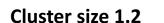
Cluster size - Epi vs Cz std and n-gap

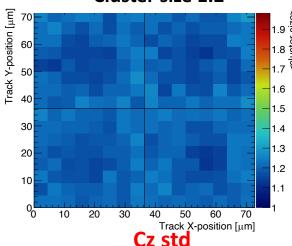




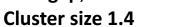


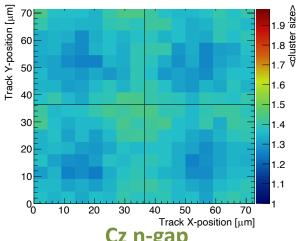
W7R1 Cz std, SUB=-50V





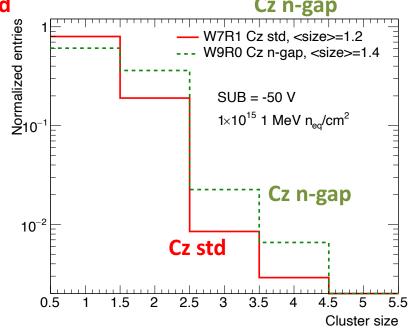
W9R0 Cz n-gap, SUB=-50V





Cluster size after irradiation at -50V

- $1x10^{15}$ MeV n_{eq} /cm² at DESY with 3 GeV electron beam
- **Cz standard** more affected by irradiation: From 1.8 to 1.2
- Cz n-gap modification less affected: From 1.4 to 1.2





MALTA CZ – Efficiency and Cluster size



Sr-90 measurements in the lab

IDB: Threshold for the discriminator

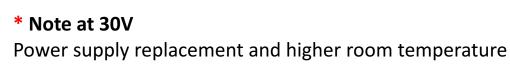
ITHR: Pulse duration of the amplifier output

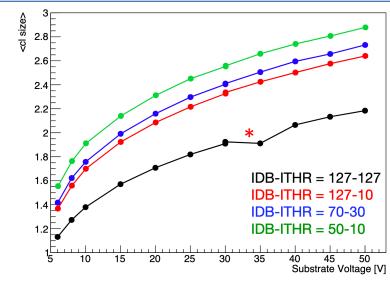
Cluster size

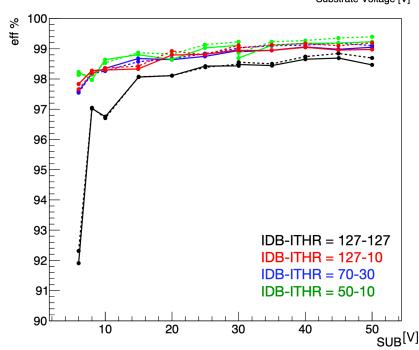
 We observe a smooth increase when increasing the voltage

Efficiency

 Large discontinuities observed at 8V to ~12V and slighter over 30V



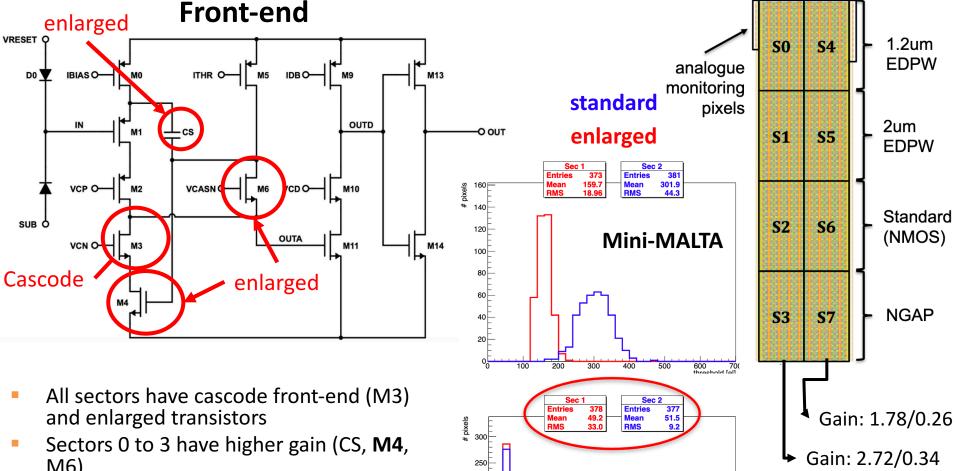




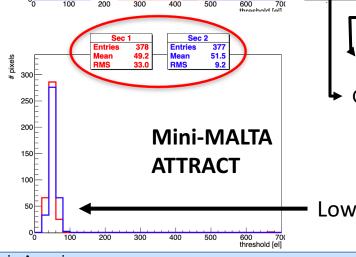


Mini-MALTA ATTRACT





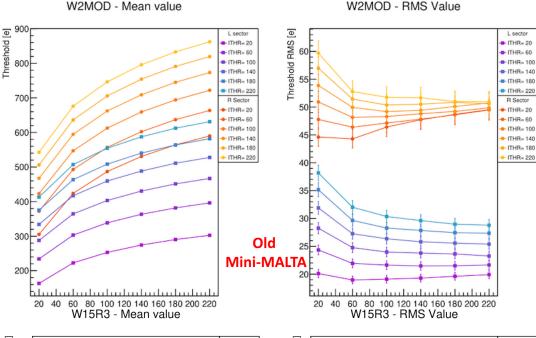
- M6)
- Sectors 0 and 4 are 1.2 um EDPW
- Sectors 1 and 5 are 2 um EDPW
- Sectors 2 and 6 are standard n-layer
- Sectors 3 and 7 are NGAP

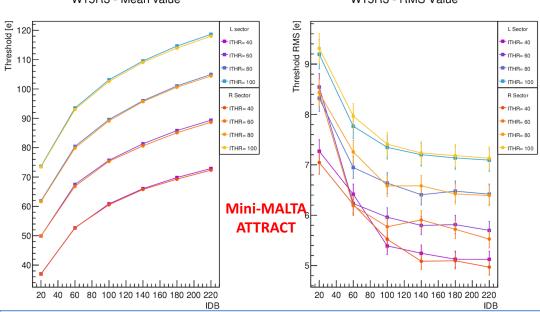




Mini-MALTA ATTRACT - threshold - IDB







Mini-MALTA ATTRACT with full cascoded front-end

- Preliminary results
- Improvements in Front-end control and threshold
- Cascoded FE allows to reach thresholds below 100e
- Also more consistent values between enlarged and standard transistors

PWELL = -6V

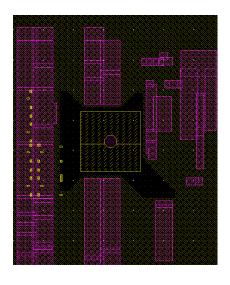


MALTA 2

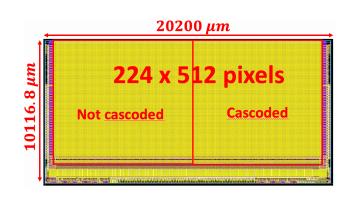


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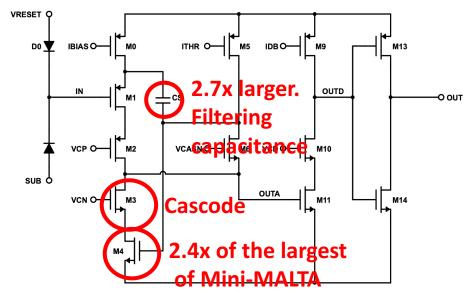
- Submission on mid October 2020
- 20.2x10.1mm sensor. Almost half size of MALTA
- Matrix of 224x512 pixels of 36.4 um size
- New sensor with gain optimized to improve time resolution
- 4322 bit shift register as new Slow Control
- Enlarged transistors from Mini-MALTA
- Half sensor cascode front-end for higher gain and reduced RTS noise
- Applying all the knowledge we learnt from MALTA C, Mini-MALTA, ATTRACT and Czochralski



MALTA 2 two front-end flavors



Analog front end modifications





Conclusions



- MALTA monolithic CMOS sensor continues improving performance with Mini-MALTA and Cz versions
- Modifications n-gap and extra deep p-well show full efficiency after 100Mrad and 10¹⁵n_{eq}/cm²
- Many improvements applied to the design of MALTA 2 which will be submitted mid October



Acknowledgements



- Part of the measurements leading to these results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF).
- Part of the measurements leading to these results have been performed at the E3 beam-line at the electron accelerator ELSA operated by the university of Bonn in Nordhrein-Westfalen, Germany.
- This project has received funding from the European Union's Horizon 2020 Research and Innovation program under Grant Agreement no. 654168.(IJS, Ljubljana, Slovenia)
- Dr. Ben Phoenix, Prof. David Parker and the operators at the MC40 cyclotron in Birmingham (UK).



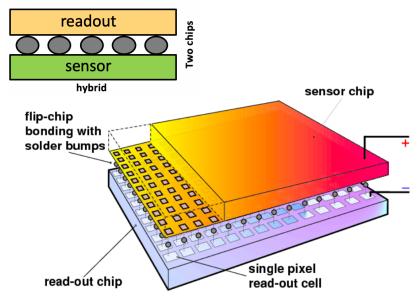


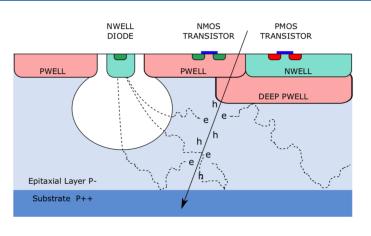
Backup



Hybrid vs Monolithic sensors







Hybrid

- Popular in current LHC detectors
- Proven radiation hardness
- Dedicated front-end electronics bonded to the sensor
- Thicker modules
- Complex and costly assembly due to fine-pitch bump bonding

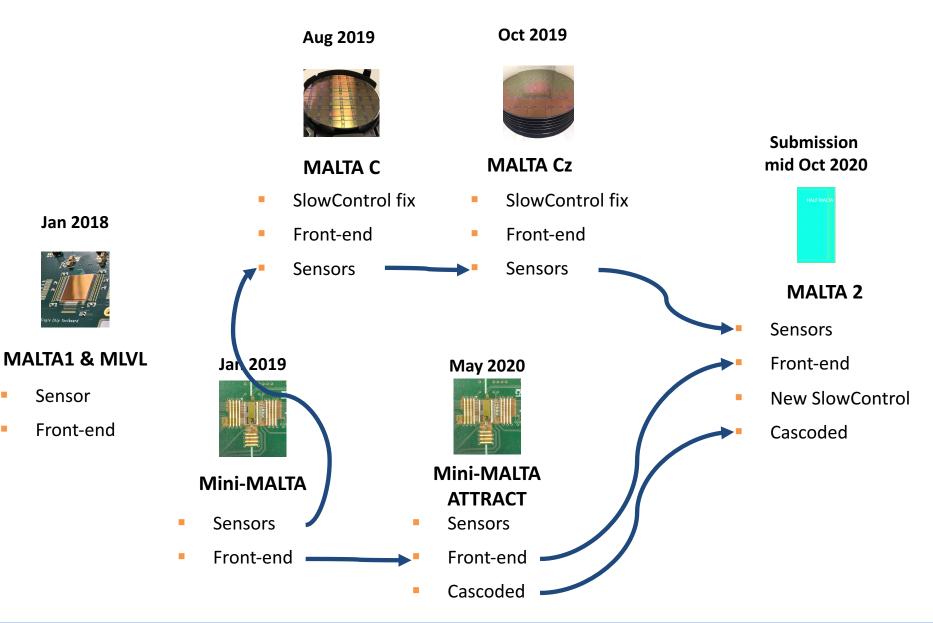
Monolithic

- Radiation hardness in research
- Electronics and sensor integrated on a single chip
- Low cost per wafer
- Thinner modules
- Substantial cost reduction and reduced module assembly time



Modifications time line overview





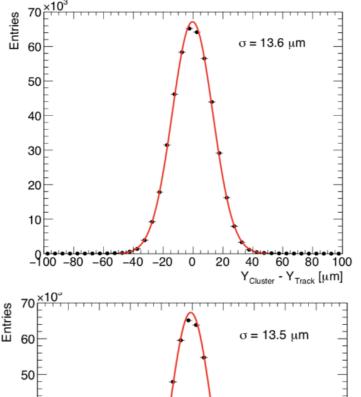


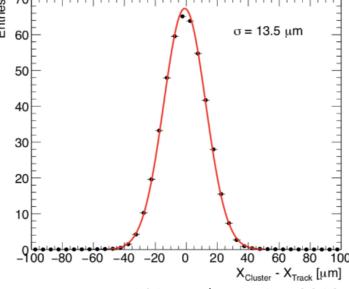
MALTA telescope tracking



Using General Broken Lines (GBL) algorithm to mitigate multiple scattering effects

- Tracking resolution
 - Distance from the cluster barycenter to the track intercept using a clusterizer algorithm
- Embedded in Proteus software
- Using MALTA Cz un-irradiated





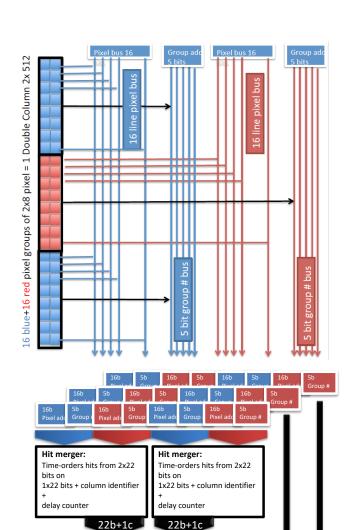
From ELSA test beam Apr 2019



MALTA read-out architecture



- Novel asynchronous readout architecture for high hit rate capability with 40 bit parallel data bus for data streaming
 - Groups of 2x8 pixels with pattern assignment to reduce data size from clusters
 - Front-end discriminator output is processed by a double-column digital logic
 - Pulse width adjustable between 0.5 ns and 2 ns
 - Data transmitted asynchronously over high speed bus to end of column
- At the periphery, arbitration and merging resolves timing conflicts of simultaneous signals
 - Timing information stored in dedicated bits
 - Output signals transmitted by 5 Gbps LVDS driver
- Virtex VC707 implementation
 - 38 asynchronous oversample
 - 400ps hit arrival precision



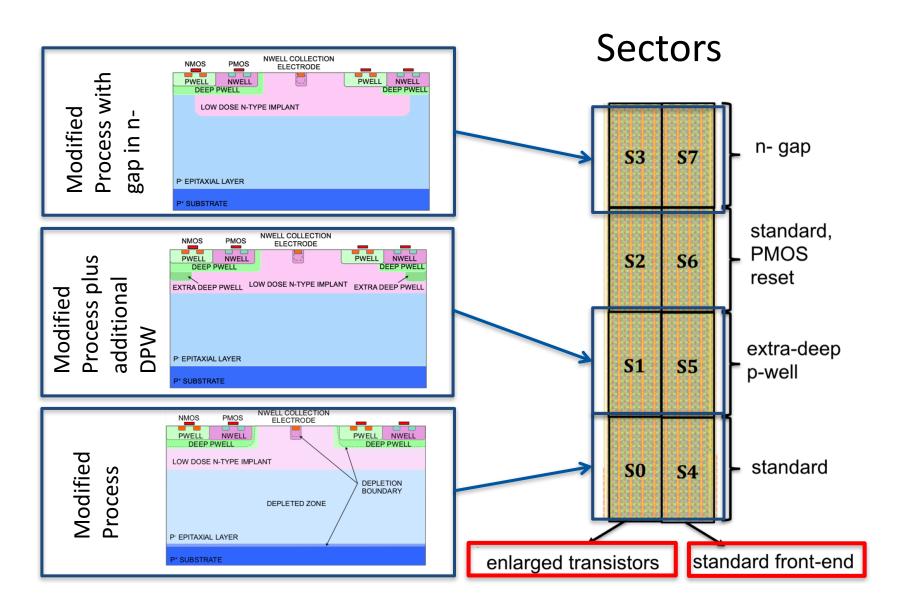
Hit merger:

Time-orders hits from 2x22 bits on 1x22 bits + column identifier +



Mini-MALTA

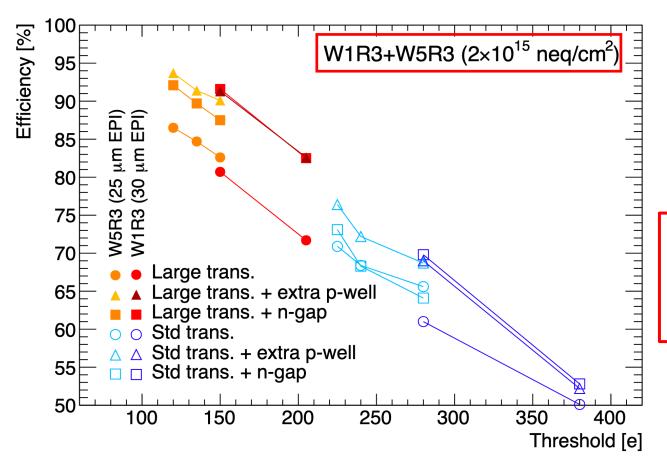






Mini-MALTA efficiency vs threshold





- Efficiency above 97% sensor modification with enlarged transitions
- Higher efficiency for enlarged transistors
- Efficiency above 90% after 2e15 n_{eq}/cm² irradiation (see backup slide)

Efficiency versus threshold for two different Mini-MALTA samples, neutron irradiated to 2e15 n_{eq}/cm^2 , and measured with 2 GeV electron beam at ELSA, with 6 V bias voltage